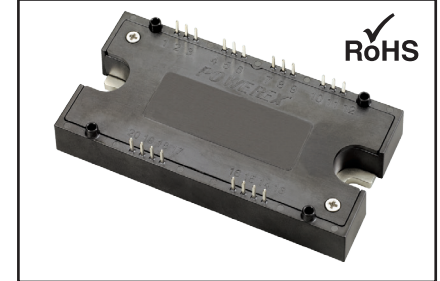
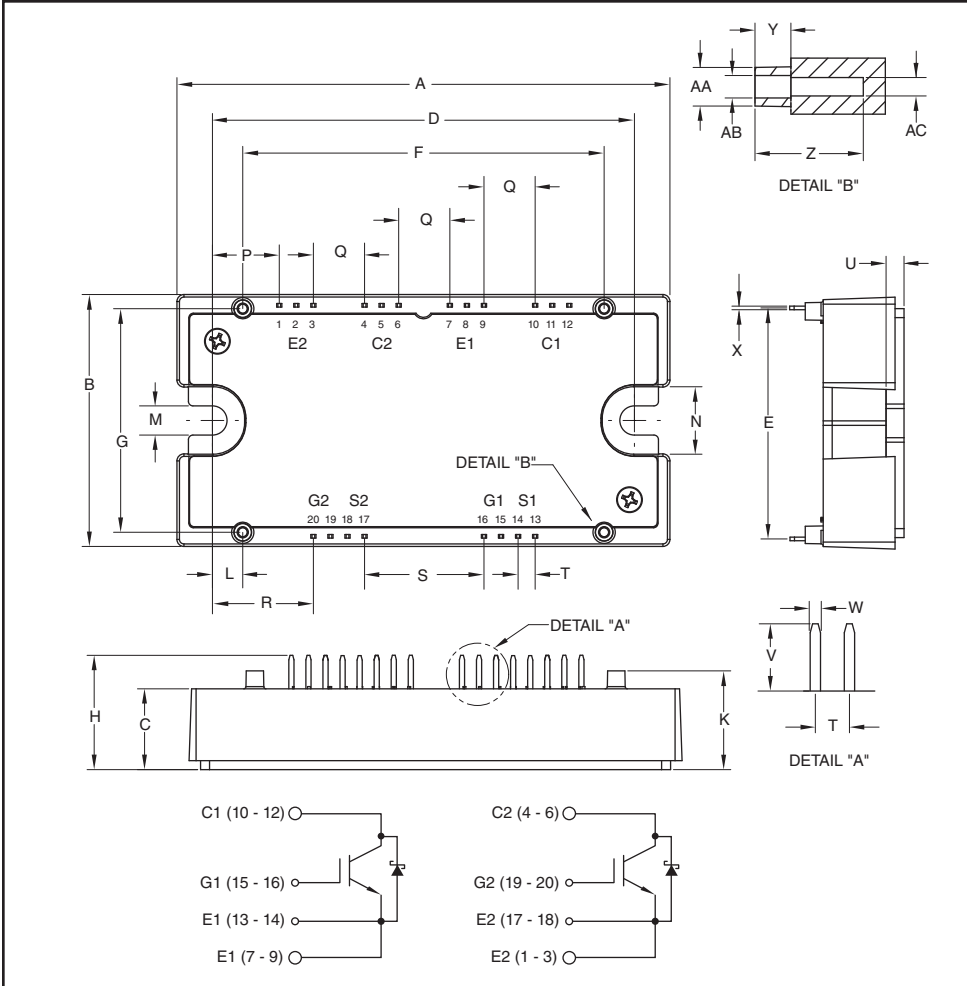


## Split Dual Si/SiC Hybrid IGBT Module 100 Amperes/1200 Volts



### Description:

Powerex IGBT Modules are designed for use in high frequency applications; upwards of 30 kHz for hard switching applications and 80 kHz for soft switching applications. Each module consists of two IGBT Transistors with each transistor having a reverse-connected super-fast recovery free-wheel silicon carbide Schottky diode. All components and interconnects are isolated from the heat sinking baseplate, offering simplified system assembly and thermal management.

### Features:

- Low ESW(off)
- Aluminum Nitride Isolation
- Discrete Super-Fast Recovery Free-Wheel Silicon Carbide Schottky Diode**
- Low Internal Inductance
- 2 Individual Switches per Module
- Isolated Baseplate for Easy Heat Sinking
- AlSiC Baseplate
- RoHS Compliant

### Applications:

- Energy Saving Power Systems such as:  
Fans; Pumps; Consumer Appliances
- High Frequency Type Power Systems such as:  
UPS; High Speed Motor Drives; Induction Heating; Welder; Robotics
- High Temperature Power Systems such as:  
Power Electronics in Electric Vehicle and Aviation Systems

### Outline Drawing and Circuit Diagram

Dimensions	Inches	Millimeters
A	4.32	109.8
B	2.21	56.1
C	0.71	18.0
D	3.70±0.02	94.0±0.5
E	2.026	51.46
F	3.17	80.5
G	1.96	49.8
H	1.00	25.5
K	0.87	22.0
L	0.266	6.75
M	0.26	6.5
N	0.59	15.0
P	0.586	14.89

Dimensions	Inches	Millimeters
Q	0.449	11.40
R	0.885	22.49
S	1.047	26.6
T	0.15	3.80
U	0.16	4.0
V	0.30	7.5
W	0.045	1.15
X	0.03	0.8
Y	0.16	4.0
Z	0.47	12.1
AA	0.17 Dia.	4.3 Dia.
AB	0.10 Dia.	2.5 Dia.
AC	0.08 Dia.	2.1 Dia.

**QID1210006**  
**Split Dual Si/SiC Hybrid IGBT Module**  
 100 Amperes/1200 Volts

**Absolute Maximum Ratings,  $T_j = 25^\circ\text{C}$  unless otherwise specified**

Ratings	Symbol	QID1210006	Units
Junction Temperature	$T_j$	-40 to 150	$^\circ\text{C}$
Storage Temperature	$T_{stg}$	-40 to 150	$^\circ\text{C}$
Collector-Emitter Voltage (G-E Short)	$V_{CES}$	1200	Volts
Gate-Emitter Voltage (C-E Short)	$V_{GES}$	$\pm 20$	Volts
Collector Current ( $T_C = 25^\circ\text{C}$ )	$I_C$	100*	Amperes
Peak Collector Current	$I_{CM}$	200*	Amperes
Emitter Current** ( $T_C = 25^\circ\text{C}$ )	$I_E$	80*	Amperes
Repetitive Peak Emitter Current ( $T_C = 25^\circ\text{C}$ , $t_p = 10\text{ms}$ , Half Sine Pulse)**	$I_{EM}$	455*	Amperes
Maximum Collector Dissipation ( $T_C = 25^\circ\text{C}$ , $T_j \leq 150^\circ\text{C}$ )	$P_C$	570	Watts
Mounting Torque, M6 Mounting	—	40	in-lb
Weight	—	130	Grams
Isolation Voltage (Main Terminal to Baseplate, AC 1 min.)	$V_{ISO}$	2500	Volts

**IGBT Electrical Characteristics,  $T_j = 25^\circ\text{C}$  unless otherwise specified**

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units	
Collector-Cutoff Current	$I_{CES}$	$V_{CE} = V_{CES}$ , $V_{GE} = 0\text{V}$	—	—	1.0	mA	
Gate Leakage Current	$I_{GES}$	$V_{GE} = V_{GES}$ , $V_{CE} = 0\text{V}$	—	—	0.5	$\mu\text{A}$	
Gate-Emitter Threshold Voltage	$V_{GE(th)}$	$I_C = 10\text{mA}$ , $V_{CE} = 10\text{V}$	4.5	6.0	7.5	Volts	
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C = 100\text{A}$ , $V_{GE} = 15\text{V}$ , $T_j = 25^\circ\text{C}$	—	5.0	6.5	Volts	
		$I_C = 100\text{A}$ , $V_{GE} = 15\text{V}$ , $T_j = 125^\circ\text{C}$	—	5.0	—	Volts	
Total Gate Charge	$Q_G$	$V_{CC} = 600\text{V}$ , $I_C = 100\text{A}$ , $V_{GE} = 15\text{V}$	—	450	—	nC	
Input Capacitance	$C_{ies}$		—	—	16	nf	
Output Capacitance	$C_{oes}$	$V_{CE} = 10\text{V}$ , $V_{GE} = 0\text{V}$	—	—	1.3	nf	
Reverse Transfer Capacitance	$C_{res}$		—	—	0.3	nf	
Inductive	Turn-on Delay Time	$t_{d(on)}$	$V_{CC} = 600\text{V}$ , $I_C = 100\text{A}$ ,	—	—	TBD	ns
Load	Rise Time	$t_r$	$V_{GE1} = V_{GE2} = 15\text{V}$ ,	—	—	TBD	ns
Switch	Turn-off Delay Time	$t_{d(off)}$	$R_G = 3.1\Omega$ ,	—	—	TBD	ns
	TimeFall Time	$t_f$	Inductive Load Switching Operation	—	—	TBD	ns

\* Pulse width and repetition rate should be such that device junction temperature ( $T_j$ ) does not exceed  $T_{j(max)}$  rating.

\*\*Represents characteristics of the anti-parallel, emitter-to-collector silicon carbide Schottky diode (FWDI).

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**Reverse Schottky Diode Characteristics,  $T_j = 25\text{ }^\circ\text{C}$  unless otherwise specified**

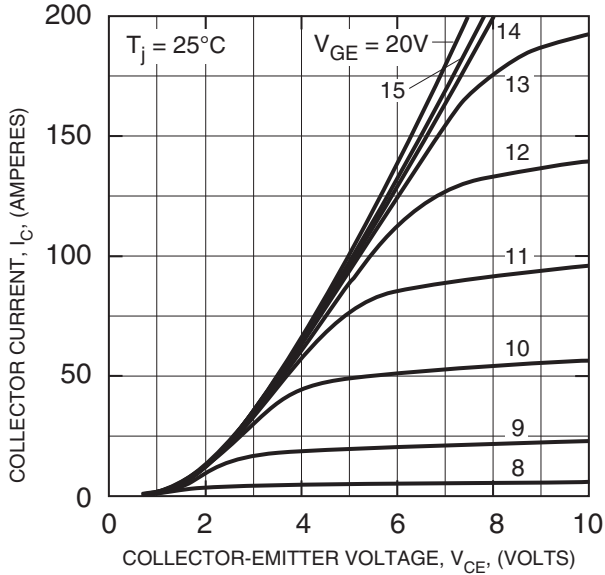
Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Diode Forward Voltage	$V_{FM}$	$I_F = 80\text{A}, V_{GS} = -5\text{V}$	—	1.6	2.0	Volts
		$I_F = 80\text{A}, V_{GS} = -5\text{V}, T_j = 175^\circ\text{C}$	—	2.5	3.2	Volts
Diode Reverse Current	$I_R$	$V_R = 1200\text{V}$	—	140	800	$\mu\text{A}$
		$V_R = 1200, T_j = 150^\circ\text{C}$	—	260	1600	$\mu\text{A}$
Diode Capacitive Charge	$Q_C$	$V_R = 1200\text{V}, I_F = 80\text{A}, di/dt = 800\text{A}/\mu\text{s}$	—	520	—	nC

**Thermal and Mechanical Characteristics,  $T_j = 25\text{ }^\circ\text{C}$  unless otherwise specified**

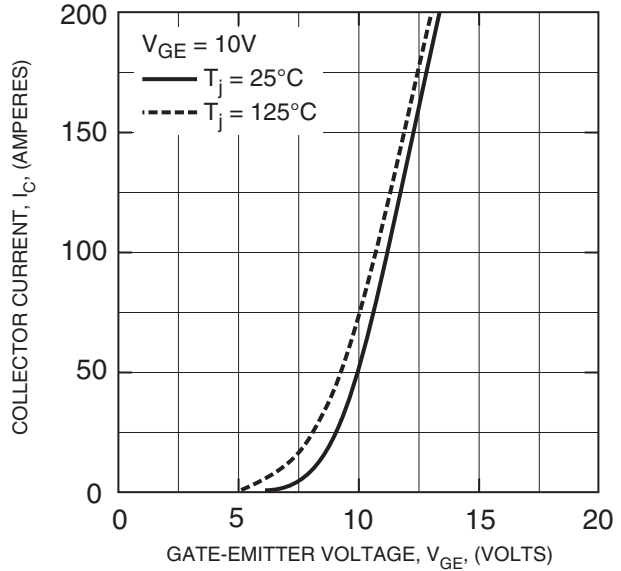
Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal Resistance, Junction to Case	$R_{th(j-c)Q}$	Per IGBT 1/2 Module,	—	—	0.217	$^\circ\text{C}/\text{W}$
		$T_C$ Reference Point Under Chips				
Thermal Resistance, Junction to Case	$R_{th(j-c)D}$	Per FWDi 1/2 Module, $T_C$ Reference	—	—	0.368	$^\circ\text{C}/\text{W}$
		$T_C$ Reference Point Under Chips				
Contact Thermal Resistance	$R_{th(c-f)}$	Per 1/2 Module, Thermal Grease Applied	—	0.04	—	$^\circ\text{C}/\text{W}$
External Gate Resistance	$R_G$		3.1	—	31	$\Omega$
Internal Inductance	$L_{int}$	IGBT Part	—	10	—	nH

**QID1210006**  
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 100 Amperes/1200 Volts

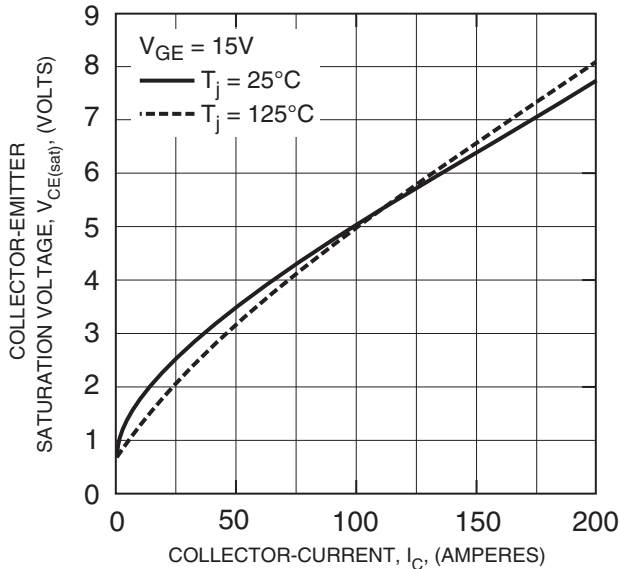
**OUTPUT CHARACTERISTICS (TYPICAL)**



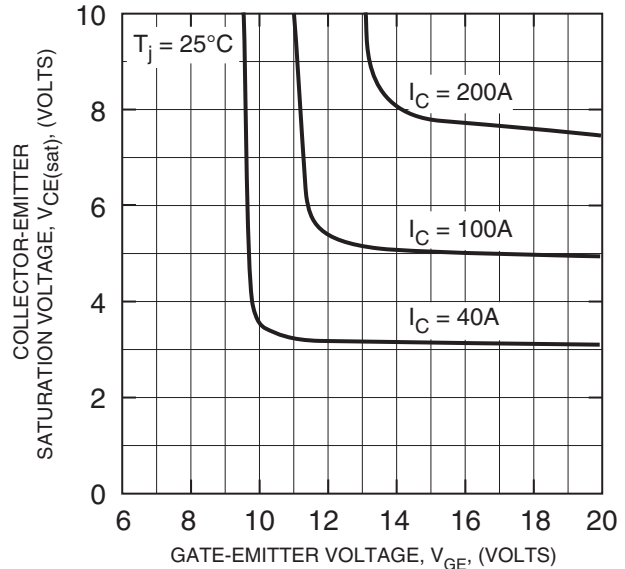
**TRANSFER CHARACTERISTICS (TYPICAL)**



**COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)**



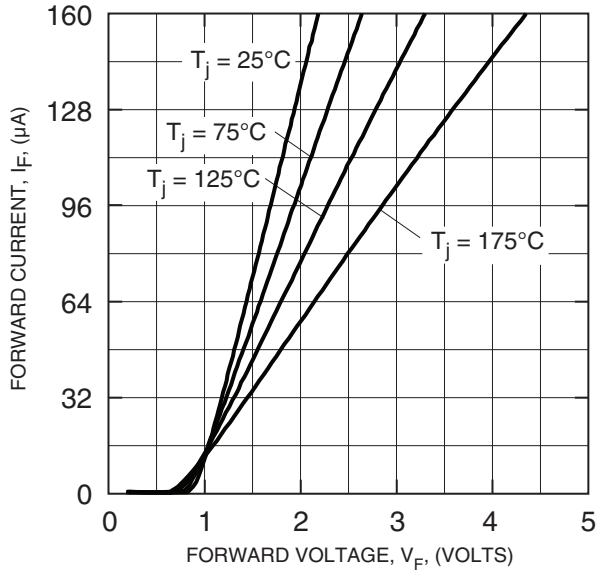
**COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)**



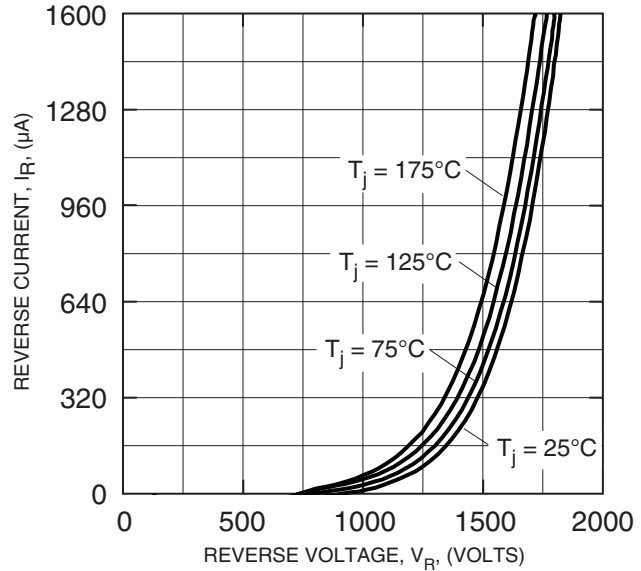
Information presented is based upon manufacturers testing and projected capabilities. This information is subject to change without notice. The manufacturer makes no claim as to the suitability of use, reliability, capability, or future availability of this product.

**QID1210006**  
**Split Dual Si/SiC Hybrid IGBT Module**  
 100 Amperes/1200 Volts

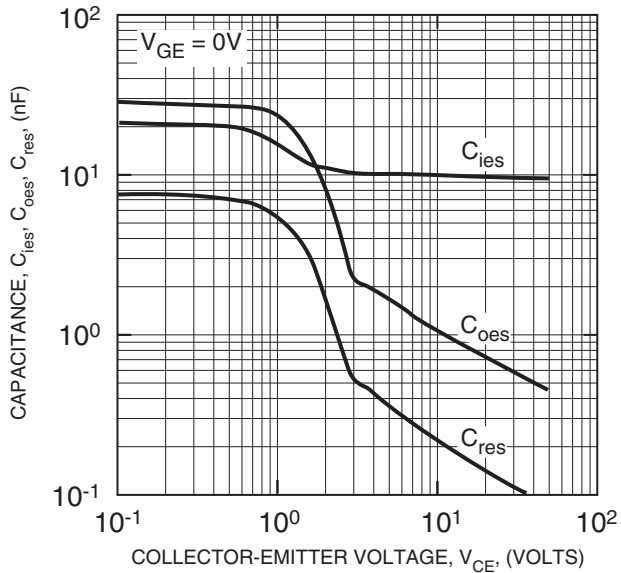
**FREE-WHEEL SCHOTTKY DIODE FORWARD CHARACTERISTICS (TYPICAL)**



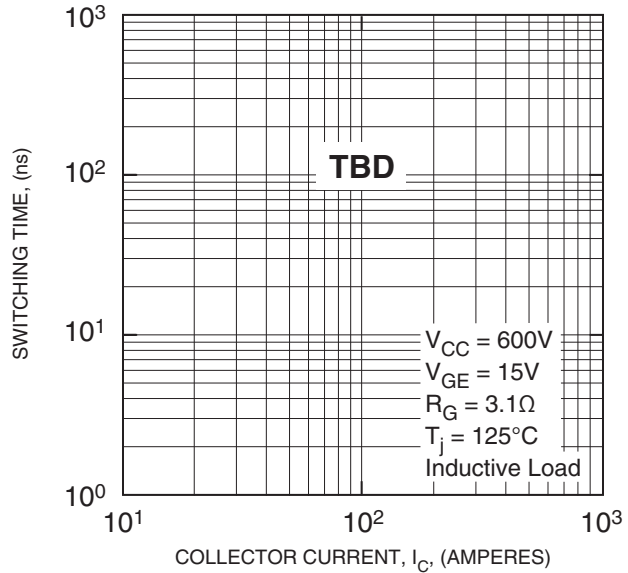
**FREE-WHEEL SCHOTTKY DIODE REVERSE CHARACTERISTICS (TYPICAL)**



**CAPACITANCE VS.  $V_{CE}$  (TYPICAL)**



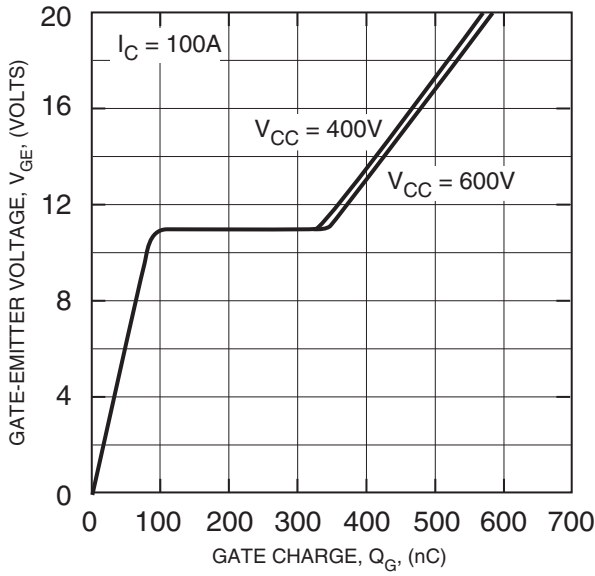
**HALF-BRIDGE SWITCHING CHARACTERISTICS (TYPICAL)**



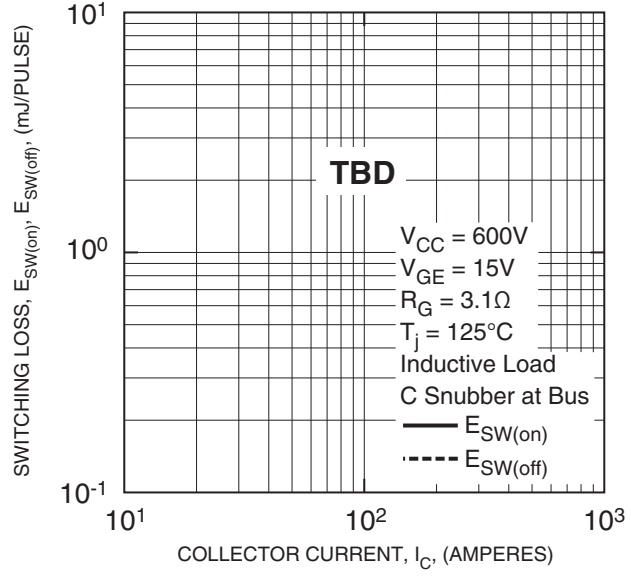
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**QID1210006**  
**Split Dual Si/SiC Hybrid IGBT Module**  
 100 Amperes/1200 Volts

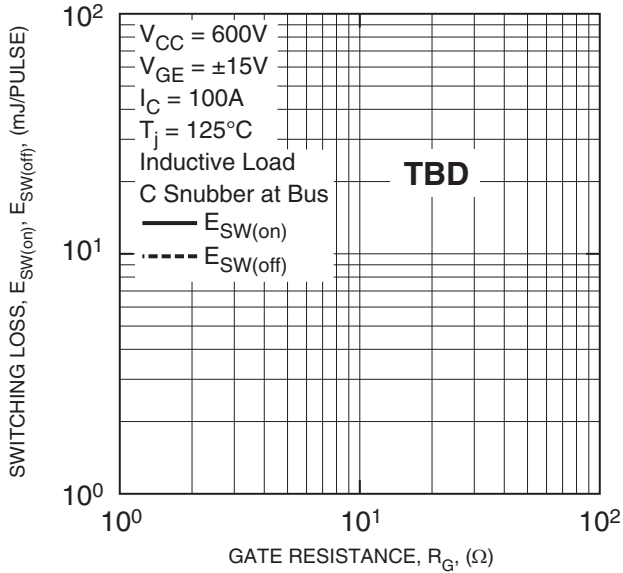
**GATE CHARGE VS.  $V_{GE}$**



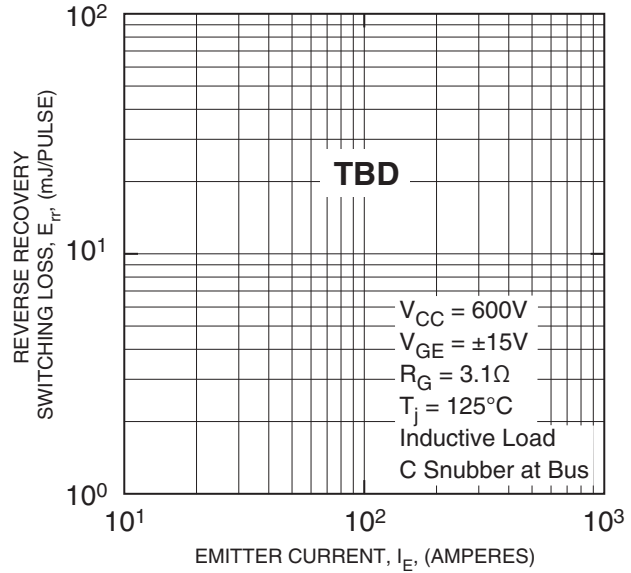
**SWITCHING LOSS VS. COLLECTOR CURRENT (TYPICAL)**



**SWITCHING LOSS VS. GATE RESISTANCE (TYPICAL)**



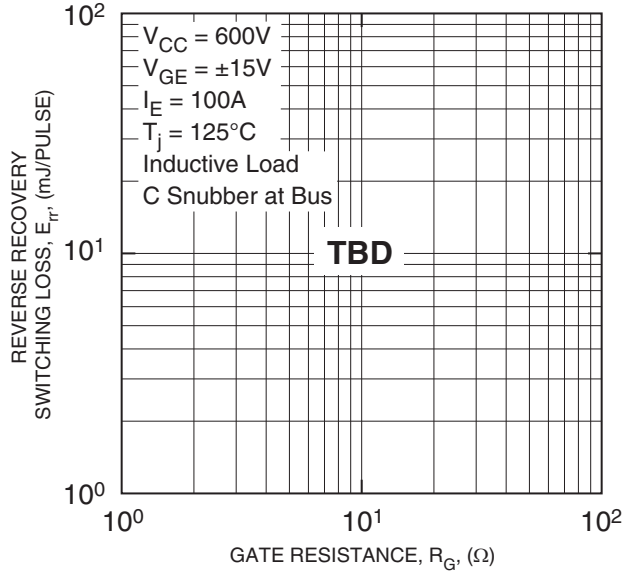
**REVERSE RECOVERY SWITCHING LOSS VS. EMITTER CURRENT (TYPICAL)**



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**QID1210006**  
**Split Dual Si/SiC Hybrid IGBT Module**  
 100 Amperes/1200 Volts

**REVERSE RECOVERY SWITCHING LOSS VS. GATE RESISTANCE (TYPICAL)**



**TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS (IGBT & FWDi)**

